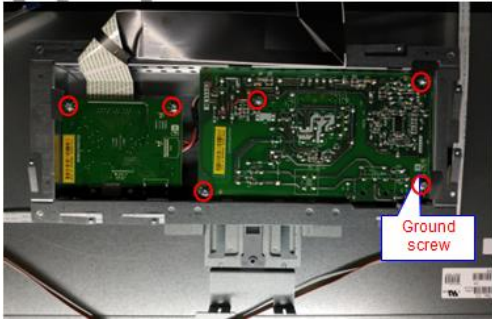
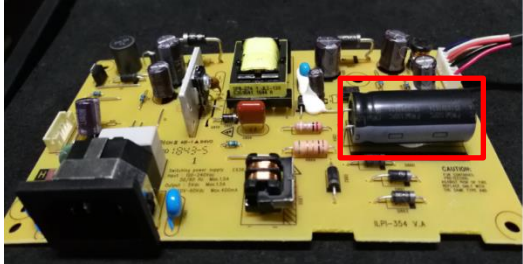
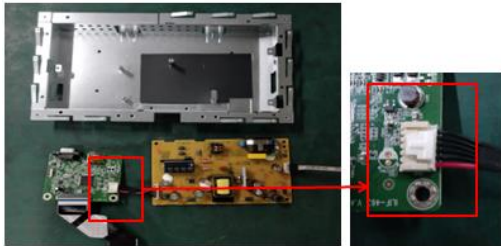
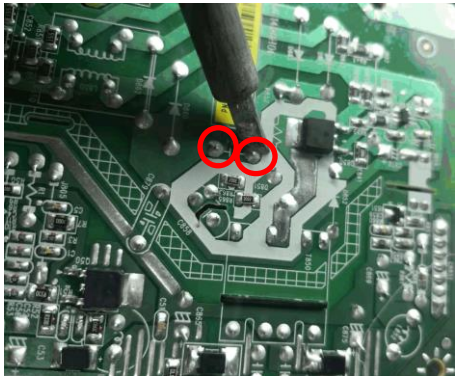
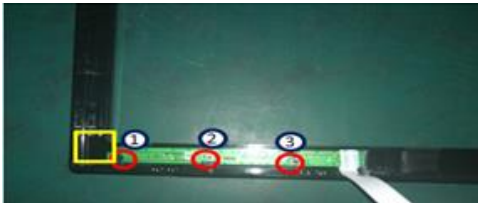


DELL SE2216H/SE2216HV/SE2216HM

1. Disassemble Procedures

<p>S1</p>	<p>Turn off power Unplug cables from monitor.</p> 	<p>S4</p>	<p>Dismantle mid frame and back cover (start with top of monitor).</p> 
<p>S2</p>	<p>Remove stand from monitor release button (with Philip-head screwdriver)</p> 	<p>S5</p>	<p>Flip the monitor to remove back cover</p> 
<p>S3</p>	<p>Use Philips-head screwdriver ($\Phi 5$ mm) to remove 2 screws for unlocking. M4 x 10, Torque = 12 +/- 1Kgf.cm *For VGA connectivity, use hexagonal screwdriver to remove 2 VGA screws. Torque = 0.8 +/- 0.1Kgf.cm</p> 	<p>S6</p>	<p>Remove acetate tape on top of backlight cable & aluminium foil on top of LVDS cable. Press the hook for both side to unplug LVDS cable. Remove mylar on top of power board.</p> 

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<p>S7</p>	<p>Use Philips-head screwdriver ($\Phi 5$ mm) to remove PCBAs screws. M3 x 5 (5pcs for VGA connectivity) & M3 x 6 for ground screw. Torque = 6.0 kgf +/-0.5 kgf</p> 	<p>S10</p>	<p>Remove electrolyte capacitor >25mm height (red mark) from printed circuit boards. Cut the glue between bulk cap and PCBA with knife – ensure cutting path within the glue, don't touch bulk cap and PCBA.</p> 
<p>S8</p>	<p>Take out Power Board and Interface Board from chassis. Remove cable from IF & power board.</p> 	<p>S11</p>	<p>Remove electrolyte capacitor >25mm height (red mark) from printed circuit boards. Cut the glue between bulk cap and PCBA with knife – ensure cutting path within the glue, don't touch bulk cap and PCBA.</p> 
<p>S9</p>	<p>Remove mylar (as yellow) Use Philips-head screwdriver ($\Phi 3$ mm) to remove 3 screws from Keypad board T2 *3. Torque: 1.0 +/- 0.1Kgf.cm</p> 	<p>S12</p>	<p>Lift the bulk capacitor away from power board.</p>

2. Product Material Information

The following substances, preparation, or components should be disposed of or recovered separately from other WEEE in compliance with Article 4 of EU Council Directive 75/422/EEC.

Capacitors / Condensers (containing PCB/PCT)	Not used
Mercury containing components	Not used
Batteries	Not used
Printed circuit boards (with surface greater than 10 square cm)	Product has printed circuit boards (with surface greater than 10 square cm)
Component contain toner, ink and liquids	Not used
Plastic containing BFR	
Component and waste contain asbestos	Not used
CRT	Not used
Component contain CFC, HCFC, HGC and HC	Not used
Gas discharge lamps	Not use
LCD display > 100 cm2	Product LCD greater than 100cm2
External electric cable	Product has external cables
Component contain refractory ceramic fibers	Not used
Component contains radio-active substances	Not used
Electrolyte capacitors (height > 25mm, diameter >25mm)	Product has electrolyte capacitors (height > 25mm)

3. Tools Required

List the type and size of the tools that would typically can be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description:-

- Screwdriver (Philip head with $\Phi 5$ mm & $\Phi 3$ mm)
- Screwdriver (Hexgonal to remove VGA connectivity)
- Soldering iron
- Knife